

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions and listings of claims in the application:

LISTING OF CLAIMS:

1. (previously presented): A semiconductor package comprising:

a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, the flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of said flexible substrate, the first electrode being connected to said device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate has at least two or more layers of patterned wiring formed thereon.

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2. (previously presented): The semiconductor package according to claim 1, wherein

said flexible substrate has a groove or a portion having less number of wiring layers formed at a bend of said flexible substrate or on a region including the bent.

3. (previously presented): The semiconductor package according to claim 2, wherein

said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.

4. (previously presented): The semiconductor package according to claim 1, wherein

said flexible substrate includes portions which are folded back to be directly adhered to each other, the folded-back portions defining a recessed portion, said semiconductor device being disposed within said recessed portion.

5. (previously presented): The semiconductor package according to claim 1, wherein

said flexible substrate has a cavity formed on said flexible substrate so as to accommodate said semiconductor device in said cavity portion.

6. (previously presented): A semiconductor package comprising:

a semiconductor device with one or more device-side electrodes being formed on a circuit-bearing surface; and

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a flexible substrate having a patterned wiring and a thermoplastic insulating layer formed on either or both sides of the patterned wiring, said flexible substrate being bent around said semiconductor device, wherein:

said flexible substrate has a first electrode provided on said semiconductor device-side surface of the flexible substrate, said first electrode being connected to the device-side electrode of said semiconductor device and sealed by said thermoplastic insulating layer, and a second electrode provided on a surface different from the surface on which said first electrode is provided; and

said flexible substrate includes portions which are folded back at bends to be directly adhered to each other.

7. (previously presented): The semiconductor package according to claim 6, wherein

the semiconductor device is accommodated in a recessed portion created by the portions of said flexible substrate being folded back to be directly adhered to each other.

8. (currently amended): A stacked semiconductor package wherein a plurality of semiconductor packages of the same type or different types according to ~~any one of claims 1 to 7~~ claim 1 are electrically connected via said electrodes and three-dimensionally stacked in layers.